

## 30-V, N-Channel NexFET™ Power MOSFETs

 Check for Samples: [CSD17552Q5A](#)

### FEATURES

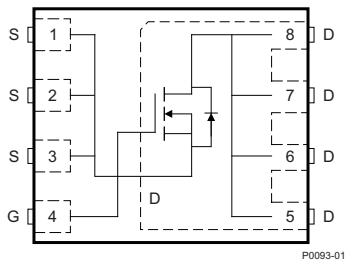
- Ultra Low Qg and Qgd
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5-mm x 6-mm Plastic Package

### APPLICATIONS

- Point of load Synchronous Buck in Networking, Telecom and Computing Systems
- Optimized for Control FET Applications

### DESCRIPTION

The NexFET power MOSFET has been designed to minimize losses in power conversion applications.

**Figure 1. Top View**


### PRODUCT SUMMARY

$V_{DS}$	Drain to Source Voltage	30	V
$Q_g$	Gate Charge Total (4.5V)	9.0	nC
$Q_{gd}$	Gate Charge Gate to Drain	2.0	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 4.5V$	6.1 mΩ
		$V_{GS} = 10V$	5.1 mΩ
$V_{GS(th)}$	Threshold Voltage	1.5	V

### ORDERING INFORMATION

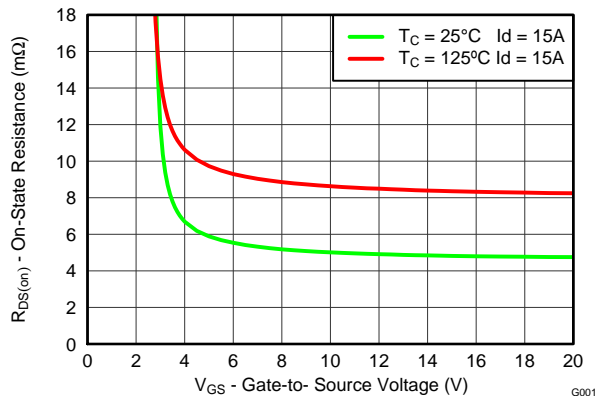
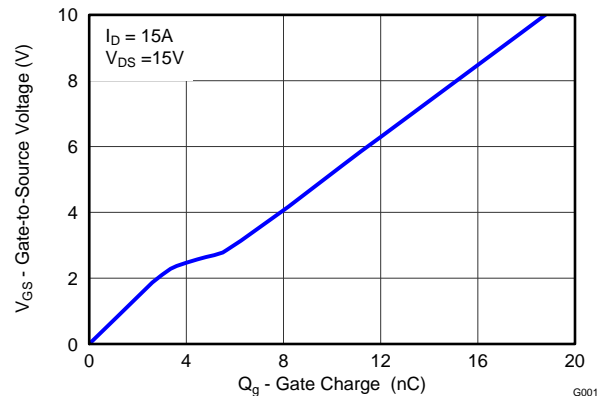
Device	Package	Media	Qty	Ship
CSD17552Q5A	SON 5-mm x 6-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

### ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ C$ unless otherwise stated		VALUE	UNIT
$V_{DS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current, $T_C = 25^\circ C$	60	A
	Continuous Drain Current, Silicon Limited	88	A
	Continuous Drain Current, $T_A = 25^\circ C^{(1)}$	17	A
$I_{DM}$	Pulsed Drain Current, $T_A = 25^\circ C^{(2)}$	106	A
$P_D$	Power Dissipation <sup>(1)</sup>	3.0	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ C$
$E_{AS}$	Avalanche Energy, single pulse $I_D = 30A, L = 0.1mH, R_G = 25\Omega$	45	mJ

(1) Typical  $R_{\theta JA} = 40^\circ C/W$  on a 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52-mm) thick FR4 PCB.

(2) Pulse duration  $\leq 300\mu s$ , duty cycle  $\leq 2\%$

 **$R_{DS(on)}$  vs  $V_{GS}$** 

**GATE CHARGE**


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

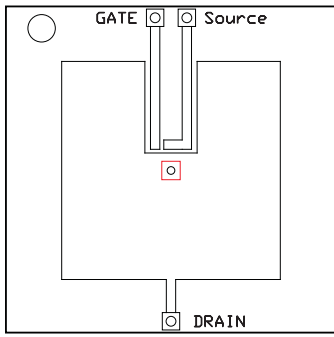
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Static Characteristics</b>						
$V_{DSS}$	Drain to Source Voltage	$V_{GS} = 0V, I_D = 250\mu A$	30			V
$I_{DSS}$	Drain to Source Leakage Current	$V_{GS} = 0V, V_{DS} = 24V$			1	$\mu A$
$I_{GSS}$	Gate to Source Leakage Current	$V_{DS} = 0V, V_{GS} = 20V$			100	nA
$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.1	1.5	1.9	V
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 4.5V, I_D = 15A$		6.1	7.5	$m\Omega$
		$V_{GS} = 10V, I_D = 15A$		5.1	6.2	$m\Omega$
$g_{fs}$	Transconductance	$V_{DS} = 15V, I_D = 15A$		77		S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		1580	2050	pF
$C_{oss}$	Output Capacitance			385	500	pF
$C_{riss}$	Reverse Transfer Capacitance			28	36	pF
$R_G$	Series Gate Resistance			0.9	1.8	$\Omega$
$Q_g$	Gate Charge Total (4.5V)	$V_{DS} = 15V, I_D = 15A$		9.0	12	nC
$Q_{gd}$	Gate Charge Gate to Drain			2.0		nC
$Q_{gs}$	Gate Charge Gate to Source			3.6		nC
$Q_{g(th)}$	Gate Charge at $V_{th}$			2.1		nC
$Q_{oss}$	Output Charge	$V_{DS} = 15V, V_{GS} = 0V$		11		nC
$t_{d(on)}$	Turn On Delay Time	$V_{DS} = 15V, V_{GS} = 4.5V,$ $I_{DS} = 15A, R_G = 2\Omega$		7.6		ns
$t_r$	Rise Time			11.4		ns
$t_{d(off)}$	Turn Off Delay Time			12.2		ns
$t_f$	Fall Time			3.6		ns
<b>Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_{SD} = 11A, V_{GS} = 0V$		0.8	1	V
$Q_{rr}$	Reverse Recovery Charge	$V_{DS} = 13V, I_F = 15A,$ $di/dt = 300A/\mu s$		20		nC
$t_{rr}$	Reverse Recovery Time			18		ns

## THERMAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

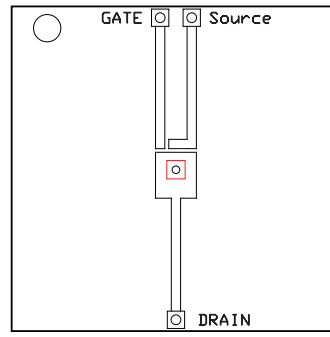
PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance Junction to Case <sup>(1)</sup>			1.8	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>(1)(2)</sup>			50	$^\circ\text{C}/\text{W}$

- (1)  $R_{\theta JC}$  is determined with the device mounted on a 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch x 1.5-inch (3.81-cm x 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB.  $R_{\theta JC}$  is specified by design, whereas  $R_{\theta JA}$  is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu.



Max  $R_{\theta JA} = 50^{\circ}\text{C/W}$   
when mounted on  
1 inch<sup>2</sup> (6.45 cm<sup>2</sup>) of 2-  
oz. (0.071-mm thick)  
Cu.

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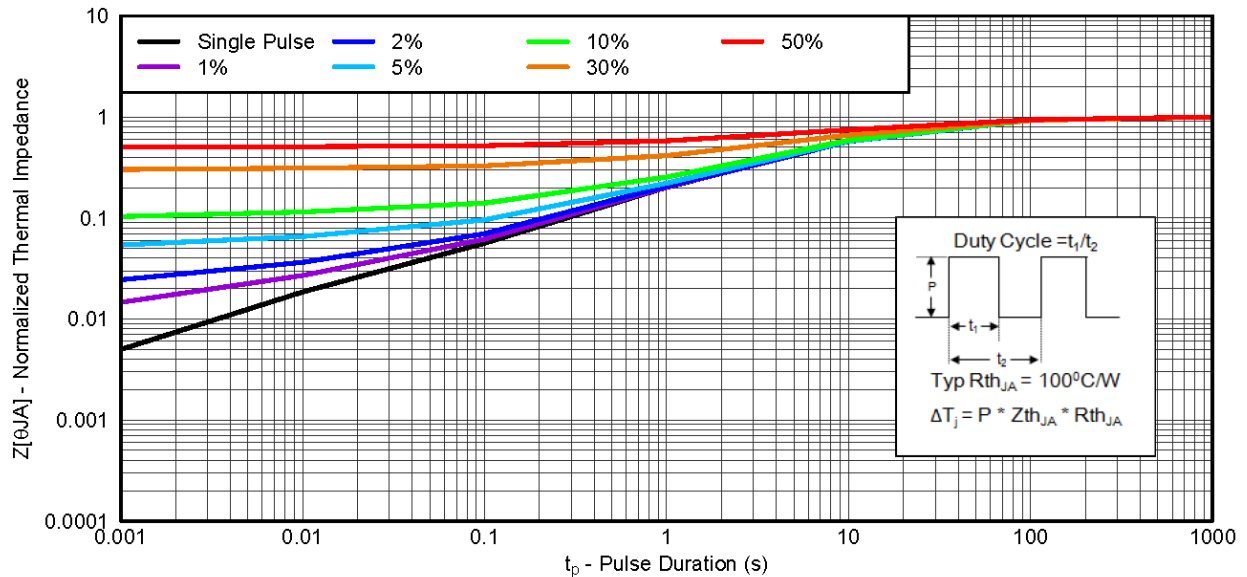


Max  $R_{\theta JA} = 125^{\circ}\text{C/W}$   
when mounted on a  
minimum pad area of  
2-oz. (0.071-mm thick)  
Cu.

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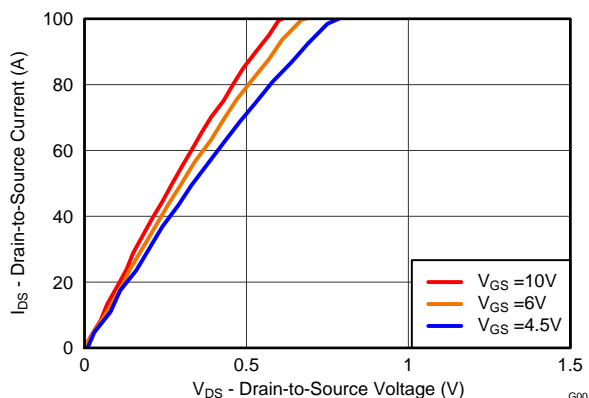
### TYPICAL MOSFET CHARACTERISTICS

( $T_A = 25^{\circ}\text{C}$  unless otherwise stated)



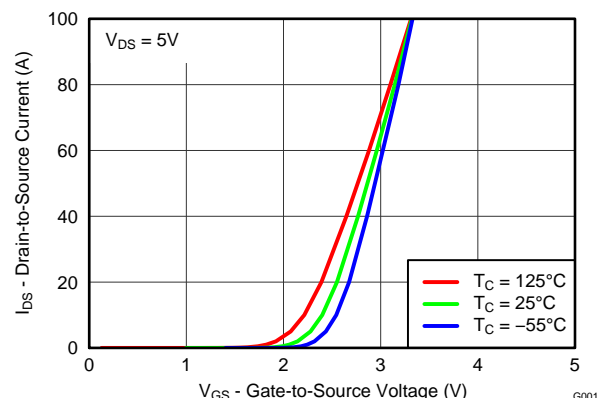
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Figure 2. Transient Thermal Impedance



G001

Figure 3. Saturation Characteristics

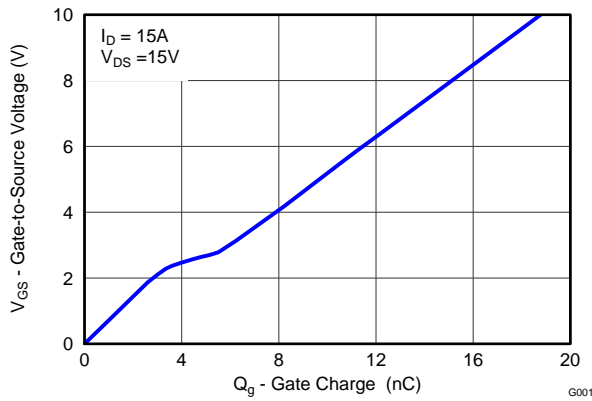


G001

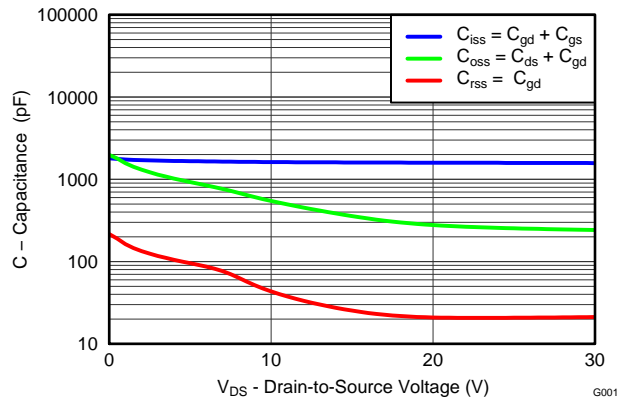
Figure 4. Transfer Characteristics

**TYPICAL MOSFET CHARACTERISTICS (continued)**

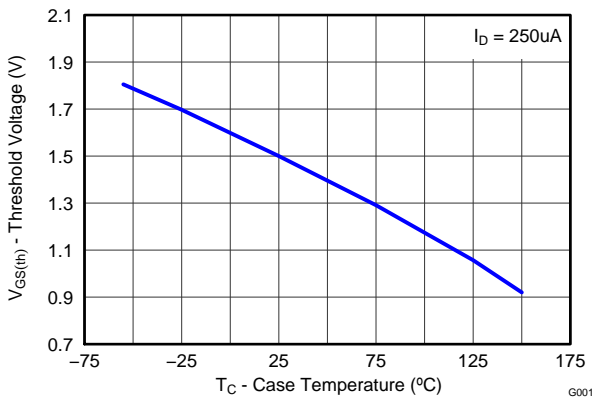
( $T_A = 25^\circ\text{C}$  unless otherwise stated)



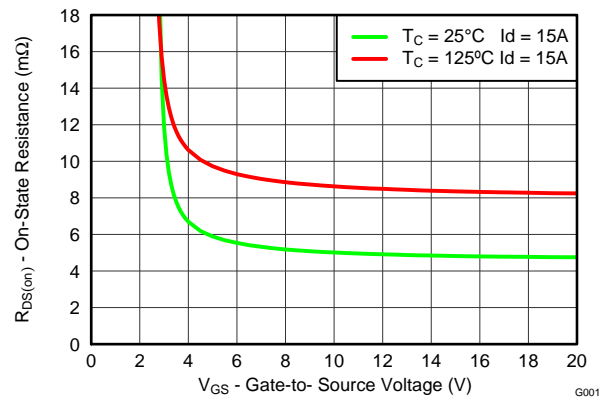
**Figure 5. Gate Charge**



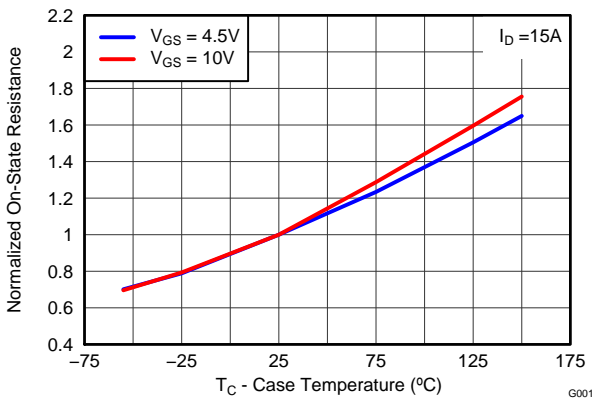
**Figure 6. Capacitance**



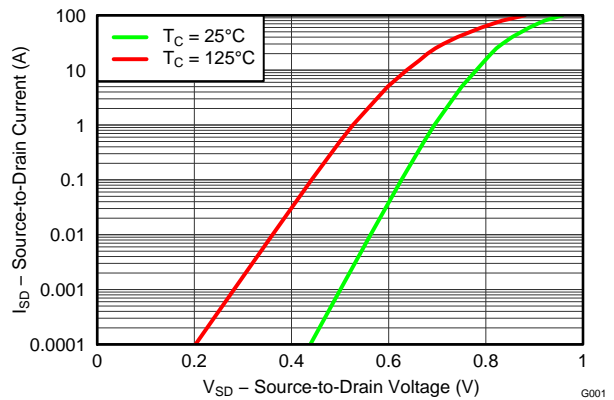
**Figure 7. Threshold Voltage vs. Temperature**



**Figure 8. On-State Resistance vs. Gate-to-Source Voltage**



**Figure 9. Normalized On-State Resistance vs. Temperature**



**Figure 10. Typical Diode Forward Voltage**

TYPICAL MOSFET CHARACTERISTICS (continued)

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

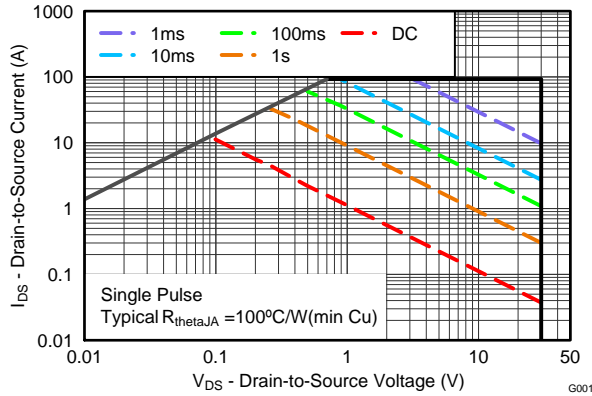


Figure 11. Maximum Safe Operating Area

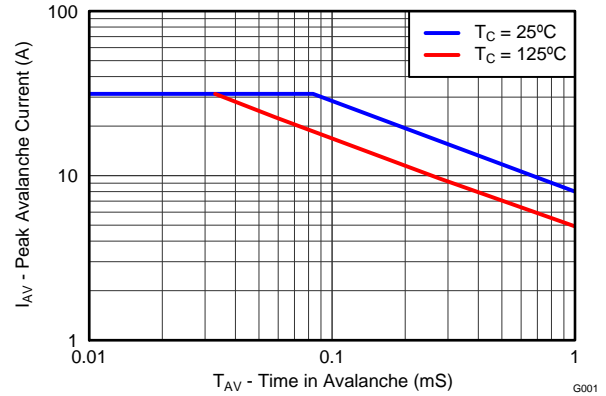


Figure 12. Single Pulse Unclamped Inductive Switching

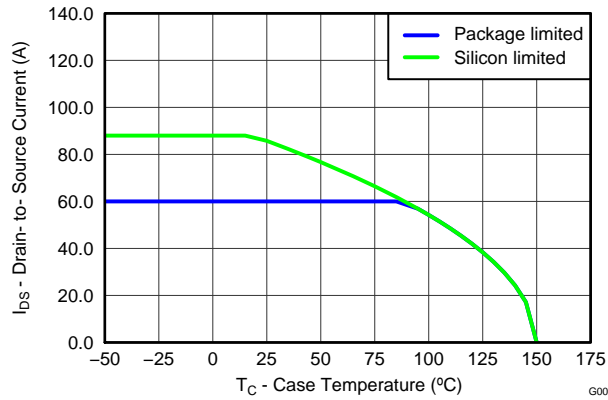
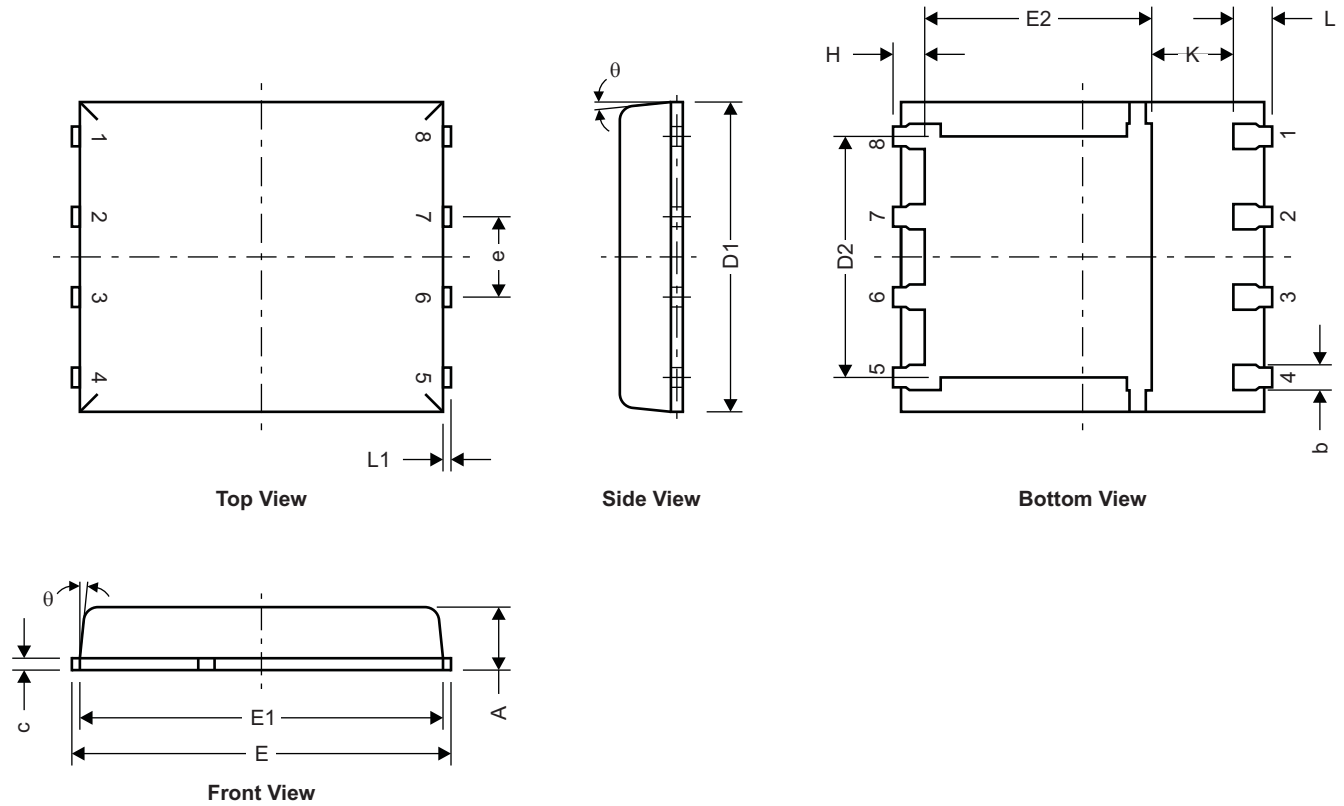


Figure 13. Maximum Drain Current vs. Temperature

**MECHANICAL DATA**

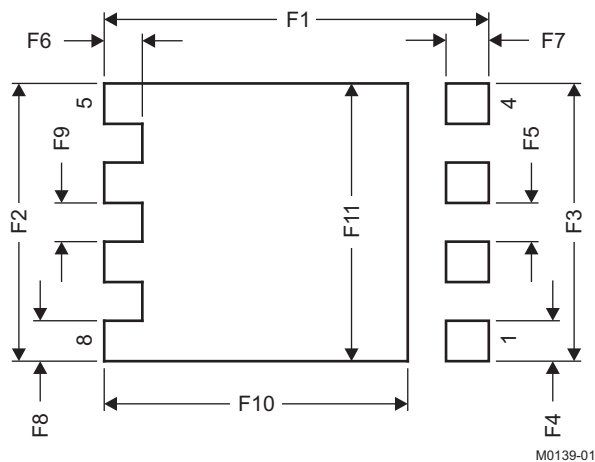
**Q5A Package Dimensions**



M0135-01

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.33	0.41	0.51
c	0.20	0.25	0.34
D1	4.80	4.90	5.00
D2	3.61	3.81	4.02
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.17	1.27	1.37
H	0.41	0.56	0.71
K	1.10		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
θ	0°		12°

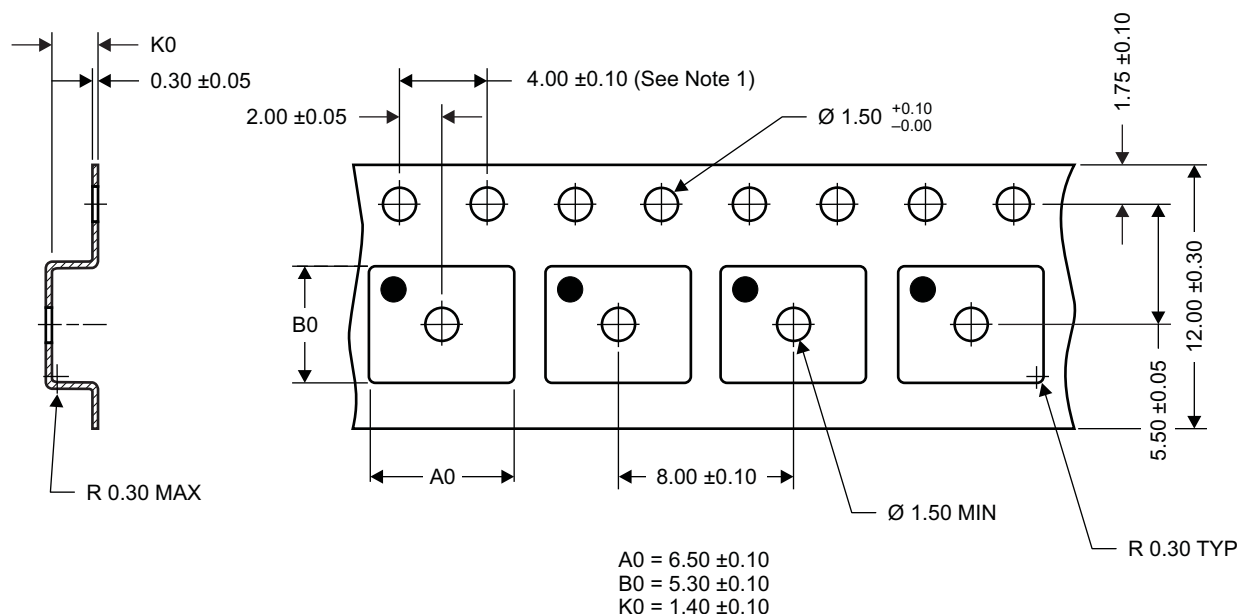
Figure 14. Recommended PCB Pattern



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.46	4.56	0.176	0.18
F3	4.46	4.56	0.176	0.18
F4	0.65	0.7	0.026	0.028
F5	0.62	0.67	0.024	0.026
F6	0.63	0.68	0.025	0.027
F7	0.7	0.8	0.028	0.031
F8	0.65	0.7	0.026	0.028
F9	0.62	0.67	0.024	0.026
F10	4.9	5	0.193	0.197
F11	4.46	4.56	0.176	0.18

For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

### Q5A Tape and Reel Information



M0138-01

### Notes:

- 10-sprocket hole-pitch cumulative tolerance  $\pm 0.2$
- Camber not to exceed 1mm in 100mm, noncumulative over 250mm
- Material: black static-dissipative polystyrene
- All dimensions are in mm (unless otherwise specified)
- A0 and B0 measured on a plane 0.3mm above the bottom of the pocket

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD17552Q5A	NRND	VSONP	DQJ	8	2500	Pb-Free (RoHS Exempt)	CU SN	Level-1-260C-UNLIM	-55 to 150	CSD17552	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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